



**HARRIS**  
SEMICONDUCTOR

January 1997

**NOT RECOMMENDED  
FOR NEW DESIGNS**  
Use CMOS Technology

# **CD54FCT245, CD74FCT245**

**BiCMOS FCT Interface Logic,  
Octal-Bus Transceivers, Three-State**

## **Features**

- Buffered Inputs
- Typical Propagation Delay: 5.0ns at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$
- Noninverting
- SCR Latchup Resistant BiCMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S
- 64mA Output Sink Current (74 Series)
- 48mA Output Sink Current (54 Series)
- Output Voltage Swing Limited to 3.7V at  $V_{CC} = 5V$
- Controlled Output Edge Rates
- Input/Output Isolation to  $V_{CC}$
- BiCMOS Technology with Low Quiescent Power

## **Description**

The CD54/74FCT245 octal bus transceiver uses a small geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output HIGH level to two diode drops below  $V_{CC}$ . This resultant lowering of output swing (0V to 3.7V) reduces power bus ringing (a source of EMI) and minimizes  $V_{CC}$  bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48mA to 64mA.

The CD54/74FCT245 is a noninverting, three-state, bidirectional transceiver/buffer intended for two-way transmission from "A" bus to "B" bus or "B" bus to "A" bus. The logic level present on the Direction Input (DIR) determines the data direction. When the Output Enable input is HIGH, the outputs are in the high impedance state.

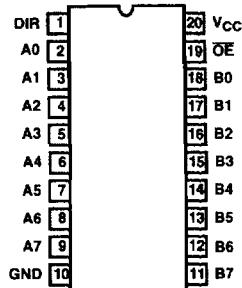
## **Ordering Information**

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74FCT245E	0 to 70	20 Ld PDIP	E20.3
CD74FCT245M	0 to 70	20 Ld SOIC	M20.3
CD74FCT245SM	0 to 70	20 Ld SSOP	M20.209
CD54FCT245E	-55 to 125	20 Ld PDIP	E20.3

NOTE: When ordering the suffix M and SM packages, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

## **Pinout**

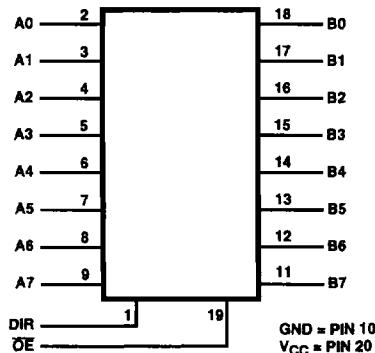
**CD54FCT245, CD74FCT245  
(PDIP, SOIC, SSOP)  
TOP VIEW**



CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

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**Functional Diagram**

TRUTH TABLE (NOTE 1)

CONTROL INPUTS		OPERATION
OE	DIR	
L	L	B Data to A Bus
L	H	A Data to B Bus
H	X	Isolation

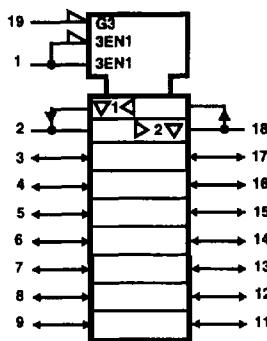
## NOTES:

1. H = High Voltage Level  
L = Low Voltage Level  
X = Irrelevant
2. To prevent excess currents in the High-Z (isolation) modes, all I/O terminals should be terminated with 10kΩ to 1 MΩ resistors.

8

BICMOS FCT  
PRODUCTS**IEC Logic Symbol**

CD74FCT245, CD54FCT245



# CD54FCT245, CD74FCT245

## Absolute Maximum Ratings

DC Supply Voltage ( $V_{CC}$ ) . . . . .	-0.5V to 6.0V
DC Input Diode Current, $I_{IK}$ (for $V_I < -0.5V$ ) . . . . .	-20mA
DC Output Diode Current, $I_{OK}$ (for $V_O < -0.5V$ ) . . . . .	-50mA
DC Output Sink Current per Output Pin, $I_O$ . . . . .	70mA
DC Output Source Current per Output Pin, $I_O$ . . . . .	-30mA
DC $V_{CC}$ Current ( $I_{CC}$ ) . . . . .	140mA
DC Ground Current ( $I_{GND}$ ) . . . . .	528mA

## Thermal Information

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package . . . . .	125
SOIC Package . . . . .	115
SSOP Package . . . . .	125
Maximum Junction Temperature . . . . .	150 $^{\circ}C$
Maximum Storage Temperature Range . . . . .	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s) . . . . .	300 $^{\circ}C$
(SOIC and SSOP-Lead Tips Only)	

## Operating Conditions

Operating Temperature Range ( $T_A$ ) . . . . .	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
CD74 Series, $T_A = 0^{\circ}C$ to 70 $^{\circ}C$ . . . . .	4.75V to 5.25V
CD54 Series, $T_A = -55^{\circ}C$ to 125 $^{\circ}C$ . . . . .	4.5V to 5.5V
DC Input Voltage, $V_I$ . . . . .	0 to $V_{CC}$
DC Output Voltage, $V_O$ . . . . .	0 to $\leq V_{CC}$
Input Rise and Fall Slew Rate, $dV/dt$ . . . . .	0 to 10ns/V

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- 8 $J_A$  is measured with the component mounted on an evaluation PC board in free air.

**Electrical Specifications** 74FCT Commercial Temperature Range 0 $^{\circ}C$  to 70 $^{\circ}C$ ;  $V_{CC}$  Max = 5.25V,  $V_{CC}$  Min = 4.75V  
54FCT Extended Industrial Temperature Range -55 $^{\circ}C$  to 125 $^{\circ}C$ ;  $V_{CC}$  Max = 5.5V,  $V_{CC}$  Min = 4.5V

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	AMBIENT TEMPERATURE ( $T_A$ )						UNITS		
		$V_I$	$I_O$ (mA)		25 $^{\circ}C$		0 $^{\circ}C$ TO 70 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$				
					MIN	MAX	MIN	MAX	MIN	MAX			
High Level Input Voltage	$V_{IH}$			4.5 to 5.5	2	-	2	-	2	-	V		
Low Level Input Voltage	$V_{IL}$			4.5 to 5.5	-	0.8	-	0.8	-	0.8	V		
High Level Output Voltage	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-15 -12	Min	2.4	-	2.4	-	-	-	V		
Low Level Output Voltage	$V_{OL}$	$V_{IH}$ or $V_{IL}$	64 48	Min	-	0.55	-	0.55	-	-	V		
High Level Input Current	$I_{IH}$	$V_{CC}$		Max	-	0.1	-	1	-	1	$\mu A$		
Low Level Input Current	$I_{IL}$	GND		Max	-	-0.1	-	-1	-	-1	$\mu A$		
Three-State Leakage Current	$I_{OZH}$ $I_{OZL}$	$V_{CC}$ GND		Max	-	0.5	-	10	-	10	$\mu A$		
Short Circuit Output Current (Note 4)	$I_{OS}$	$V_{CC}$ or GND $V_O = 0$		Max	-60	-	-60	-	-60	-	mA		
Input Clamp Voltage	$V_{IK}$	$V_{CC}$ or GND	-18	Min	-	-1.2	-	-1.2	-	-1.2	V		
Quiescent Supply Current, MSI	$I_{CC}$	$V_{CC}$ or GND	0	Max	-	8	-	80	-	500	$\mu A$		
Additional Quiescent Supply Current per Input Pin TTL Inputs High, 1 Unit Load	$\Delta I_{CC}$	3.4V (Note 5)		Max	-	1.6	-	1.6	-	2	mA		

NOTES:

- Not more than one output should be shorted at one time. Test duration should not exceed 100ms.
- Inputs that are not measured are at  $V_{CC}$  or GND.
- FCT Input Loading: All inputs are 1 unit load. Unit load is  $\Delta I_{CC}$  limit specified in Static Characteristics Chart, e.g., 1.6mA Max at 70 $^{\circ}C$ .

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**Switching Specifications**  $t_r, t_f = 2.5\text{ns}$ ,  $C_L = 50\text{pF}$ ,  $R_L$  - See Figure 3

PARAMETER	SYMBOL	$V_{CC}$ (V)	AMBIENT TEMPERATURE ( $T_A$ )							UNITS	
			25°C		0°C TO 70°C			-55°C TO 125°C			
			TYP	MIN	TYP	MAX	MIN	TYP	MAX		
Propagation Delays Data to Outputs)	$t_{PLH}, t_{PHL}$	5	5	1.5	-	7	1.5	-	7.5	ns	
Output Enable to Output	$t_{PZL}, t_{PZH}$	5	6	1.5	-	7.5	1.5	-	10	ns	
Output Disable to Output	$t_{PLZ}, t_{PHZ}$	5	6	1.5	-	9.5	1.5	-	10	ns	
Power Dissipation Capacitance	$C_{PD}$	-	49	-	49	-	-	49	-	pF	
Min (Valley) $V_{OHV}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OHV}$	5	0.5	-	-	-	-	-	-	V	
Max (Peak) $V_{OLP}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OLP}$	5	1	-	-	-	-	-	-	V	
Input Capacitance	$C_I$	-	-	-	-	10	-	-	10	pF	
Input/Output Capacitance	$C_{I/O}$	-	-	-	-	15	-	-	15	pF	

NOTES:

7. 5V: Min is at 5.5V, Max is at 4.5V.  
5V: Min is at 5.25V for 0°C to 70°C, Max is at 4.75V for 0°C to 70°C, Typ is at 5V.

8.  $C_{PD}$ , measured per function, is used to determine the dynamic power consumption.

$$P_D \text{ (per package)} = V_{CC} I_{CC} + \sum (V_{CC}^2 f_i C_{PD} + V_O^2 f_O C_L + V_{CC} \Delta I_{CC} D) \text{ where:}$$

$V_{CC}$  = supply voltage

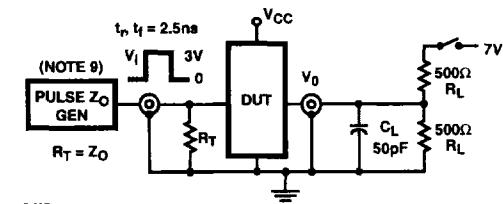
$\Delta I_{CC}$  = flow through current x unit load

$C_L$  = output load capacitance

D = duty cycle of input high

$f_O$  = output frequency

$f_i$  = input frequency

**Test Circuits and Waveforms**

NOTE:

9. Pulse Generator for All Pulses: Rate  $\leq 1.0\text{MHz}$ ;  $Z_{\text{OUT}} \leq 50\Omega$ ;  
 $t_r, t_f \leq 2.5\text{ns}$ .

FIGURE 1. TEST CIRCUIT

**SWITCH POSITION**

TEST	SWITCH
$t_{PLZ}, t_{PZL}$ , Open Drain	Closed
$t_{PZH}, t_{PZL}, t_{PLH}, t_{PHL}$	Open

**DEFINITIONS:**

$C_L$  = Load capacitance, includes jig and probe capacitance.

$R_T$  = Termination resistance, should be equal to  $Z_{\text{OUT}}$  of the Pulse Generator.

$V_{IN} = 0\text{V}$  to  $3\text{V}$ .

Input:  $t_r = t_f = 2.5\text{ns}$  (10% to 90%), unless otherwise specified

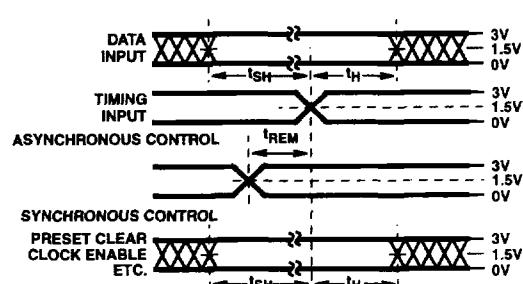


FIGURE 2. SETUP, HOLD, AND RELEASE TIMING

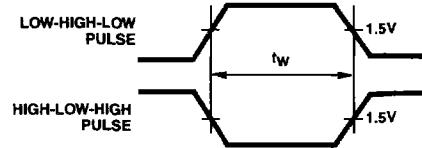


FIGURE 3. PULSE WIDTH

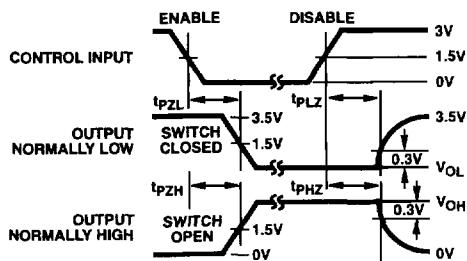


FIGURE 4. ENABLE AND DISABLE TIMING

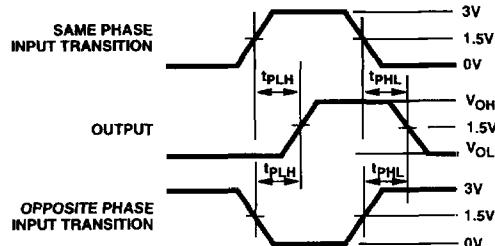
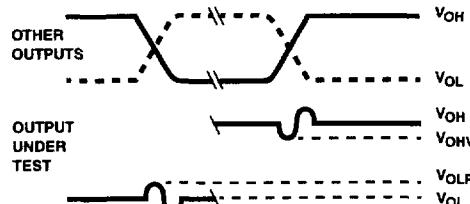


FIGURE 5. PROPAGATION DELAY

**NOTES:**

10.  $V_{OLP}$  is measured with respect to a ground reference near the output under test.  $V_{OHV}$  is measured with respect to  $V_{OH}$ .  
 11. Input pulses have the following characteristics:  
 $P_{RR} \leq 1\text{MHz}$ ,  $t_r = 2.5\text{ns}$ ,  $t_f = 2.5\text{ns}$ , skew  $1\text{ns}$ .  
 12. R.F. fixture with 700MHz design rules required. IC should be soldered into test board and bypassed with  $0.1\mu\text{F}$  capacitor. Scope and probes require 700MHz bandwidth.

FIGURE 6. SIMULTANEOUS SWITCHING TRANSIENT WAVEFORMS